

SiC MOSFET P3M12010TM

N-Channel Enhancement Mode

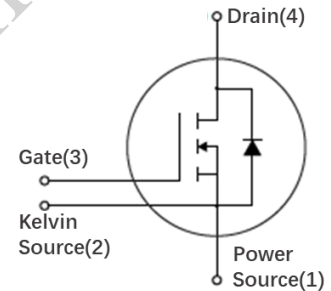
Features

- High Blocking Voltage with Low On-Resistance
- High-Frequency Operation
- Ultra-Small Q_{gd}



Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirements
- Reduction of System Cost



Applications

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies

Drain	4
Gate	3
Kelvin Source	2
Power Source	1

Order Information

Part Number	Package	Marking
P3M12010TM	TPAK	P3M12010TM

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PNJunction Semiconductor

1. Maximum Ratings

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	V_{DSmax}	1200	V	$V_{GS} = -3V$ $I_D = 100\mu A$
Gate - Source Voltage (Dynamic)	V_{GSmax}	-8 / +21	V	AC ($f > 1\text{ Hz}$)
Gate - Source Voltage (Static)	V_{GSop}	-3 / +15/+18	V	Static
Continuous Drain Current, assumes $R_{th(j-c)} < 0.19\text{ K/W}$	I_D	230	A	$V_{GS} = 18V$ $T_C = 25^\circ\text{C}$
		170		$V_{GS} = 18V$ $T_C = 100^\circ\text{C}$
Power Dissipation	P_D	1000	W	$T_C = 25^\circ\text{C}$
Operating Junction	T_J	-55 To +175	$^\circ\text{C}$	
Storage Temperature	T_{stg}	-55 To +175	$^\circ\text{C}$	

2. Electrical Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	/	/	V	$V_{GS} = -3\text{V}$ $I_D = 2.5\text{ mA}$
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.5	/	V	$V_{DS} = V_{GS}$ $I_D = 24\text{mA}$ $T_J = 25^\circ\text{C}$
		/	1.8	/	V	$V_{DS} = V_{GS}$ $I_D = 24\text{mA}$ $T_J = 175^\circ\text{C}$
Reverse Bias Drain Current	I_{DSS}	/	1	100	μA	$V_{GS} = -3\text{V}$ $V_{DS} = 1200\text{V}$
Gate-Source Leakage Current	I_{GSS}	/	10	300	nA	$V_{GS} = 18\text{V}$ $V_{DS} = 0\text{V}$
Drain-Source On-State Resistance	$R_{DS(on)}$	/	8	/	m Ω	$V_{GS} = 18\text{V}$ $I_D = 100\text{A}$ $T_J = 25^\circ\text{C}$
		/	11	/		$V_{GS} = 18\text{V}$ $I_D = 100\text{A}$ $T_J = 125^\circ\text{C}$
		/	13.5	/		$V_{GS} = 18\text{V}$ $I_D = 100\text{A}$ $T_J = 175^\circ\text{C}$
		/	10	/		$V_{GS} = 15\text{V}$ $I_D = 100\text{A}$ $T_J = 25^\circ\text{C}$

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Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Input Capacitance	C _{iss}	/	12.6	/	nF	V _{GS} = 0V V _{DS} = 800V f= 500kHz V _{AC} = 25mV
Output Capacitance	C _{oss}	/	432	/	pF	
Reverse Transfer Capacitance	C _{rss}	/	30	/	pF	
Coss Stored Energy	E _{oss}	/	170	/	μJ	
Gate to Source Charge	Q _{gs}	/	182	/	nC	V _{DS} = 800V I _{DS} = 100A V _{GS} = -3/18V I _G = 24mA
Gate to Drain Charge	Q _{gd}	/	94	/		
Total Gate Charge	Q _g	/	434	/		
Turn-on Energy	E _{on}	/	2128	/	μJ	V _{DS} = 800V I _{DS} = 100A V _{GS} = -3V/18V R _G = 1.0Ω L= 50μH
Turn-off Energy	E _{off}	/	944	/		
Turn-On Delay Time	T _{d(on)}	/	42.7	/	ns	
Rise Time	T _r	/	25.9	/		
Turn-Off Delay Time	T _{d(off)}	/	76.2	/		
Fall Time	T _f	/	21.8	/		

3. Reverse Diode Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	V_{SD}	6.2	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 100\text{A}$ $T_J = 25^\circ\text{C}$
		5.6	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 100\text{A}$ $T_J = 175^\circ\text{C}$
Reverse Recover Time	t_{rr}	31	/	ns	$V_{GS} = -3/18\text{V}$ $I_{SD} = 100\text{A}$ $V_{DS} = 800\text{V}$ $d_{if}/d_t = 5000\text{A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$
Reverse Recovery Charge	Q_{rr}	1747	/	μC	
Peak Reverse Recovery Current	I_{rrm}	94	/	A	
Reverse Recovery Energy	E_{RR}	941	/	μJ	

4. Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.15	$^\circ\text{C}/\text{W}$

5. Typical Performance

At $T_J = 25^\circ\text{C}$, unless specified otherwise

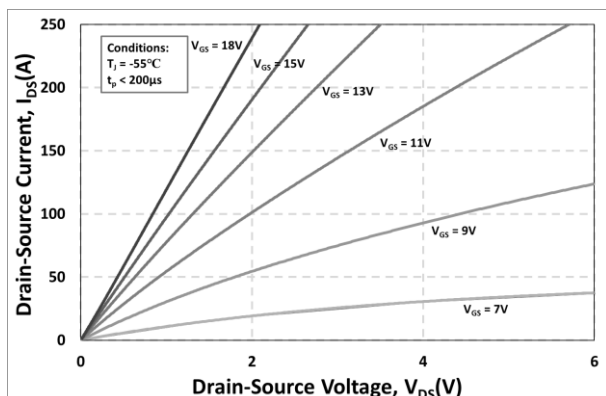


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

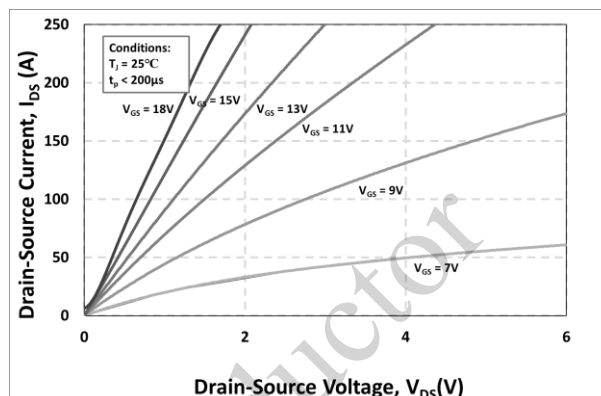


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

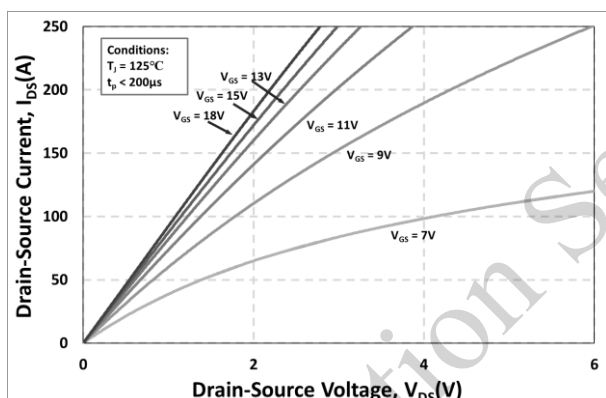


Figure 3. Output Characteristics $T_J = 125^\circ\text{C}$

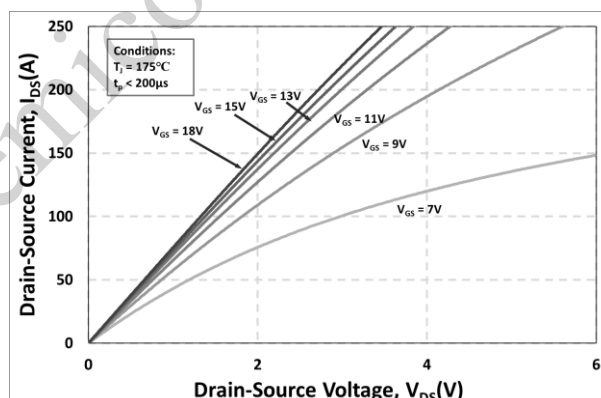


Figure 4. Output Characteristics $T_J = 175^\circ\text{C}$

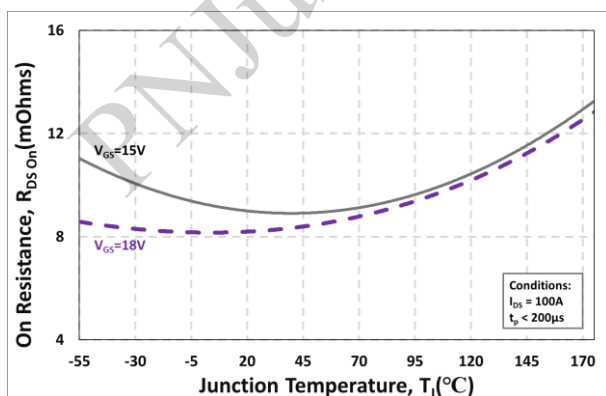


Figure 5. On-Resistance vs. Temperature

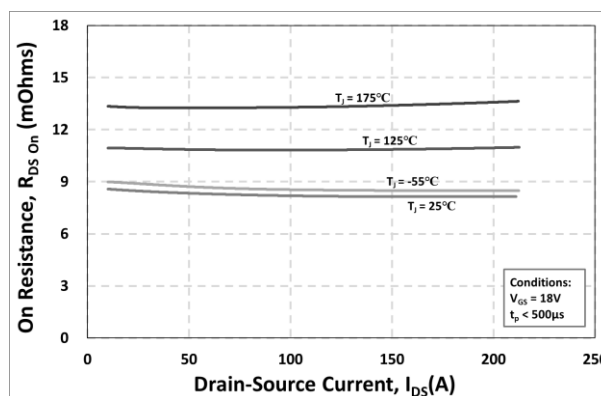


Figure 6. On-Resistance vs. Drain Current Various Temperatures

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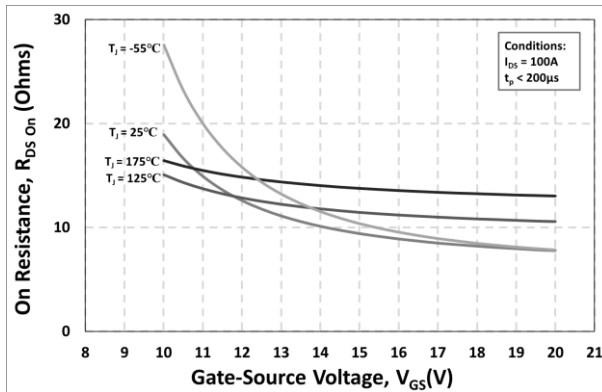


Figure 7. On-Resistance vs. Gate-Source Voltage

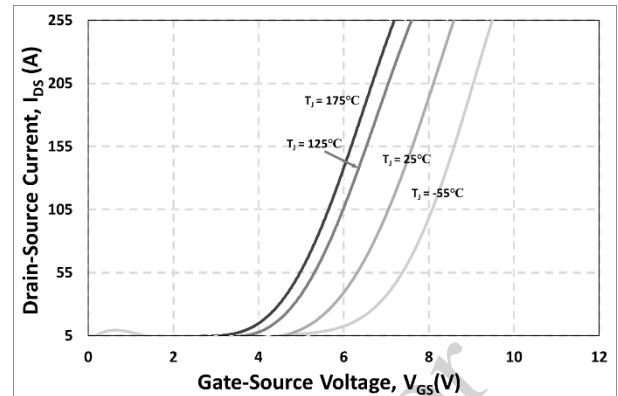


Figure 8. Transfer Characteristic for Various Junction Temperatures

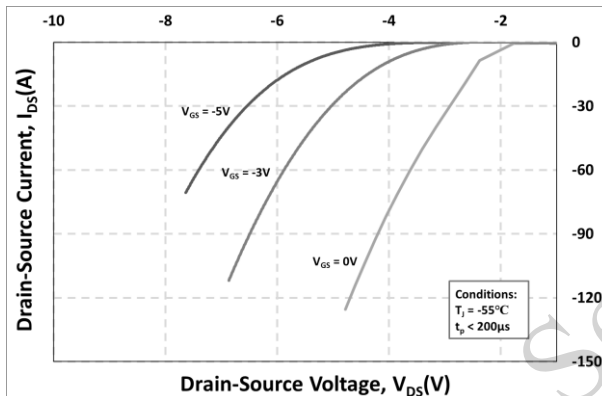


Figure 9. Body Diode Characteristic at -55°C

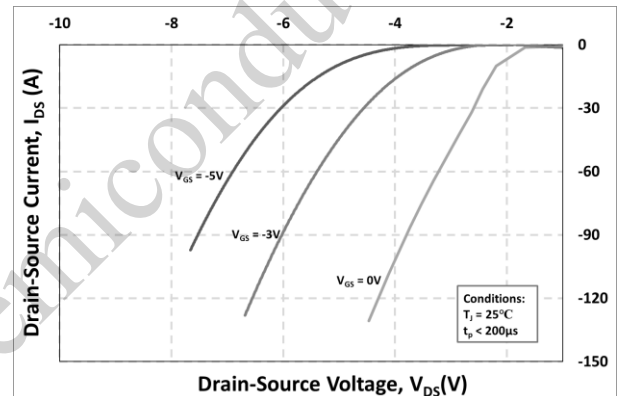


Figure 10. Body Diode Characteristic at 25°C

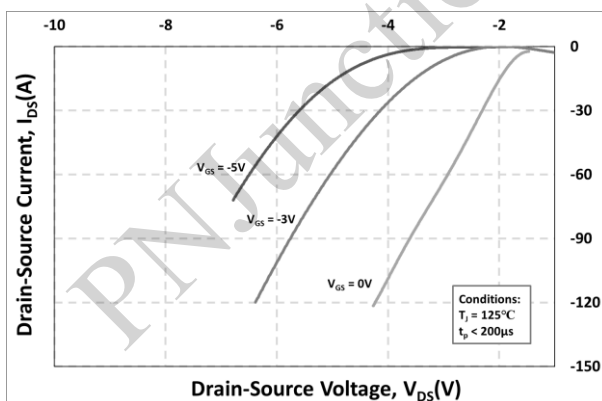


Figure 11. Body Diode Characteristic at 125°C

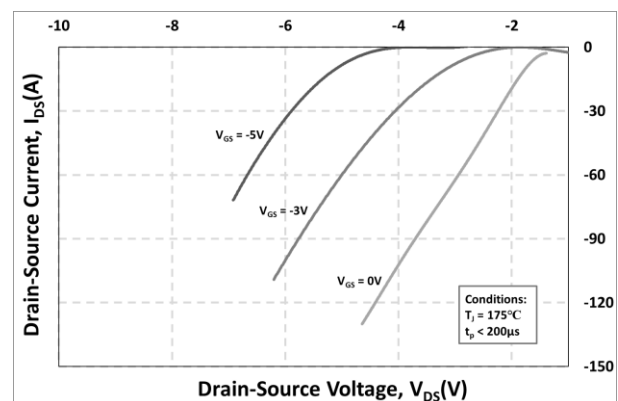


Figure 12. Body Diode Characteristic at 175°C

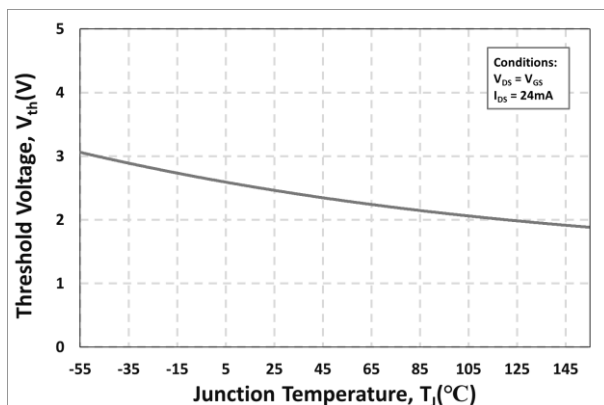


Figure 13. Threshold Voltage vs. Temperature

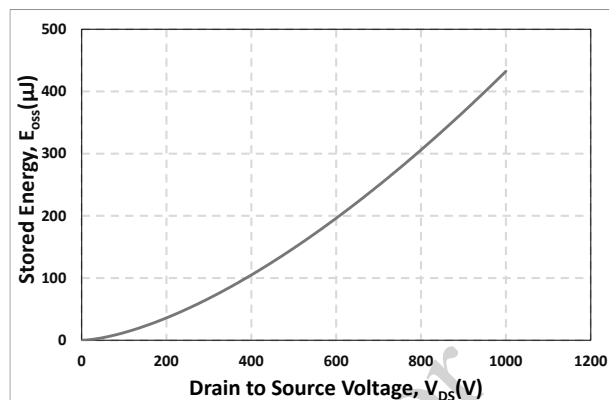


Figure 14. Output Capacitor Stored Energy

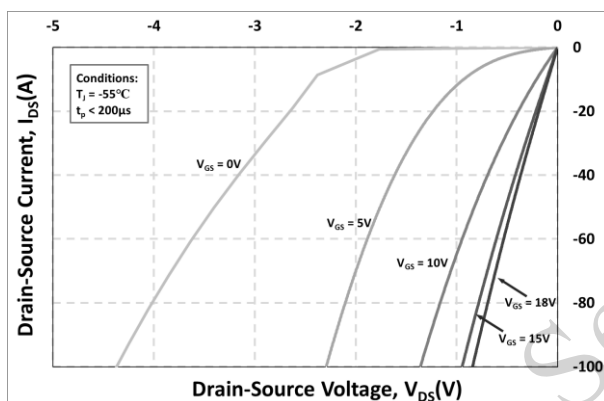


Figure 15. 3rd Quadrant Characteristic at -55°C

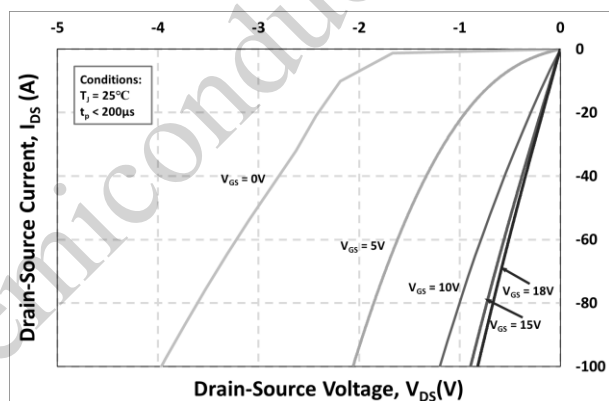


Figure 16. 3rd Quadrant Characteristic at 25°C

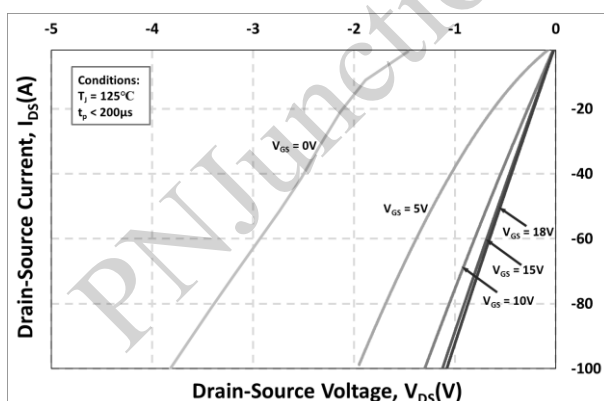


Figure 17. 3rd Quadrant Characteristic at 125°C

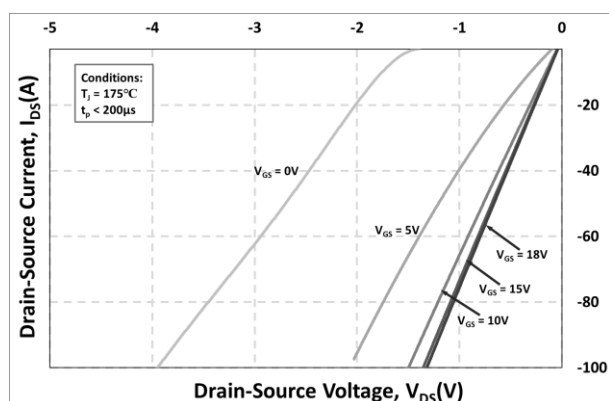


Figure 18. 3rd Quadrant Characteristic at 175°C

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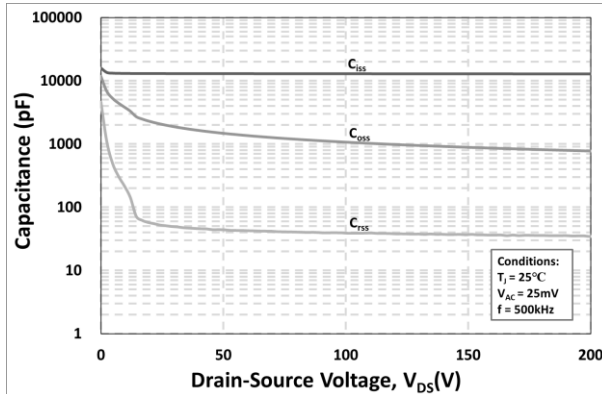


Figure 19. Capacitances vs. Drain-Source Voltage (0 - 200V)

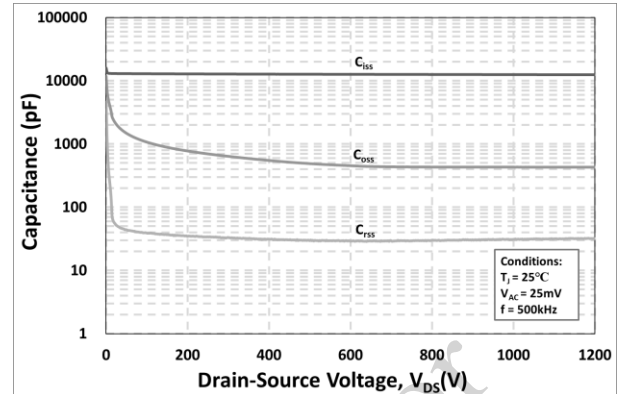


Figure 20. Capacitances vs. Drain-Source Voltage (0 - 1200V)

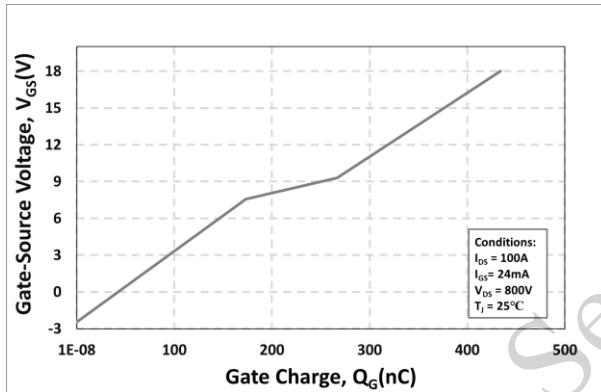


Figure 21. Gate Charge Characteristics

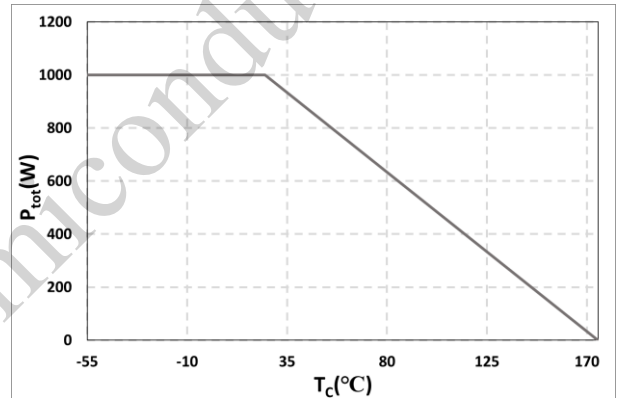


Figure 22. Maximum Power Dissipation Derating vs. Case Temperature

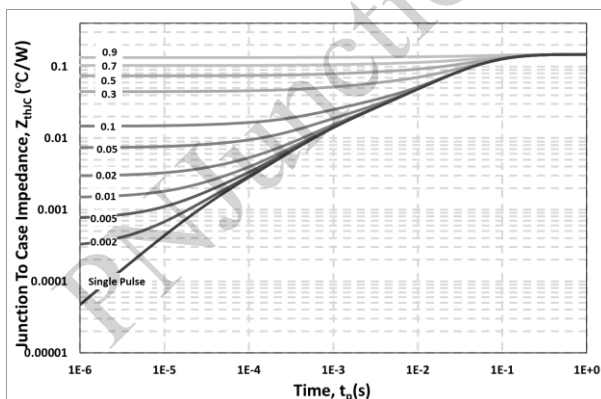


Figure 23. Transient Thermal Impedance (Junction - Case)

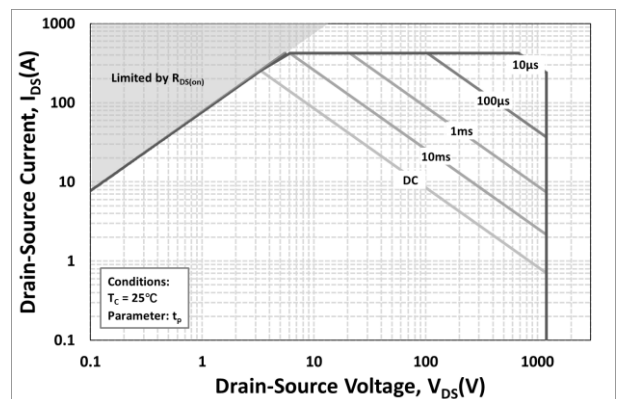


Figure 24. Forward Bias Safe Operating Area (FBSOA)

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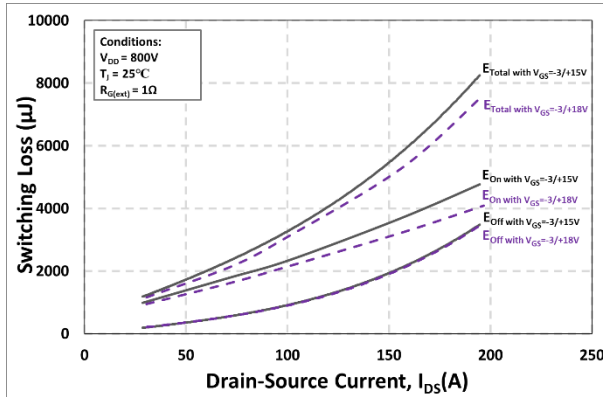


Figure 25. Switching Loss vs. Drain-Source Current (VDS = 800 V)

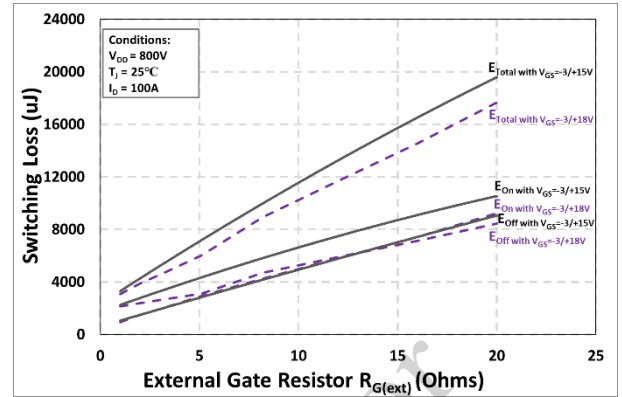


Figure 26. Switching Loss vs. External Gate Resistance

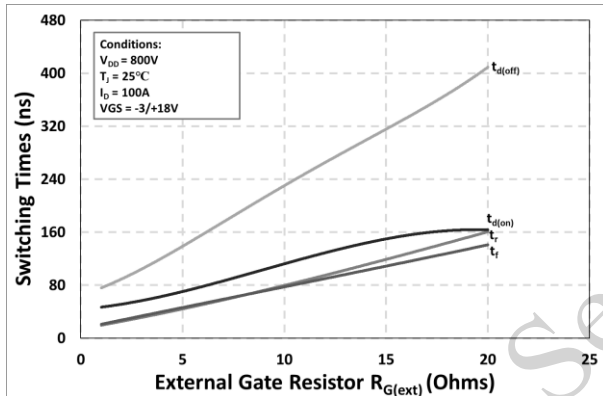


Figure 27. Switching Times vs. External Gate Resistance

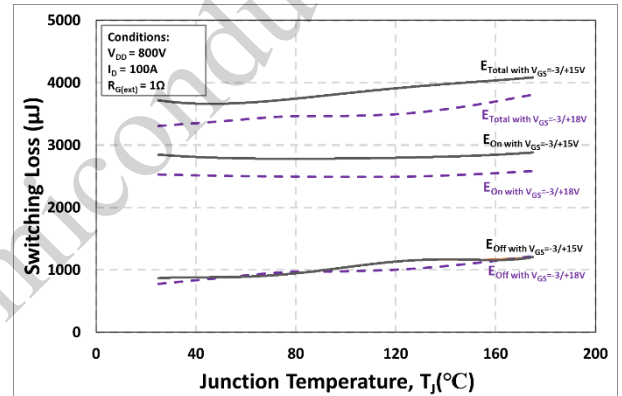
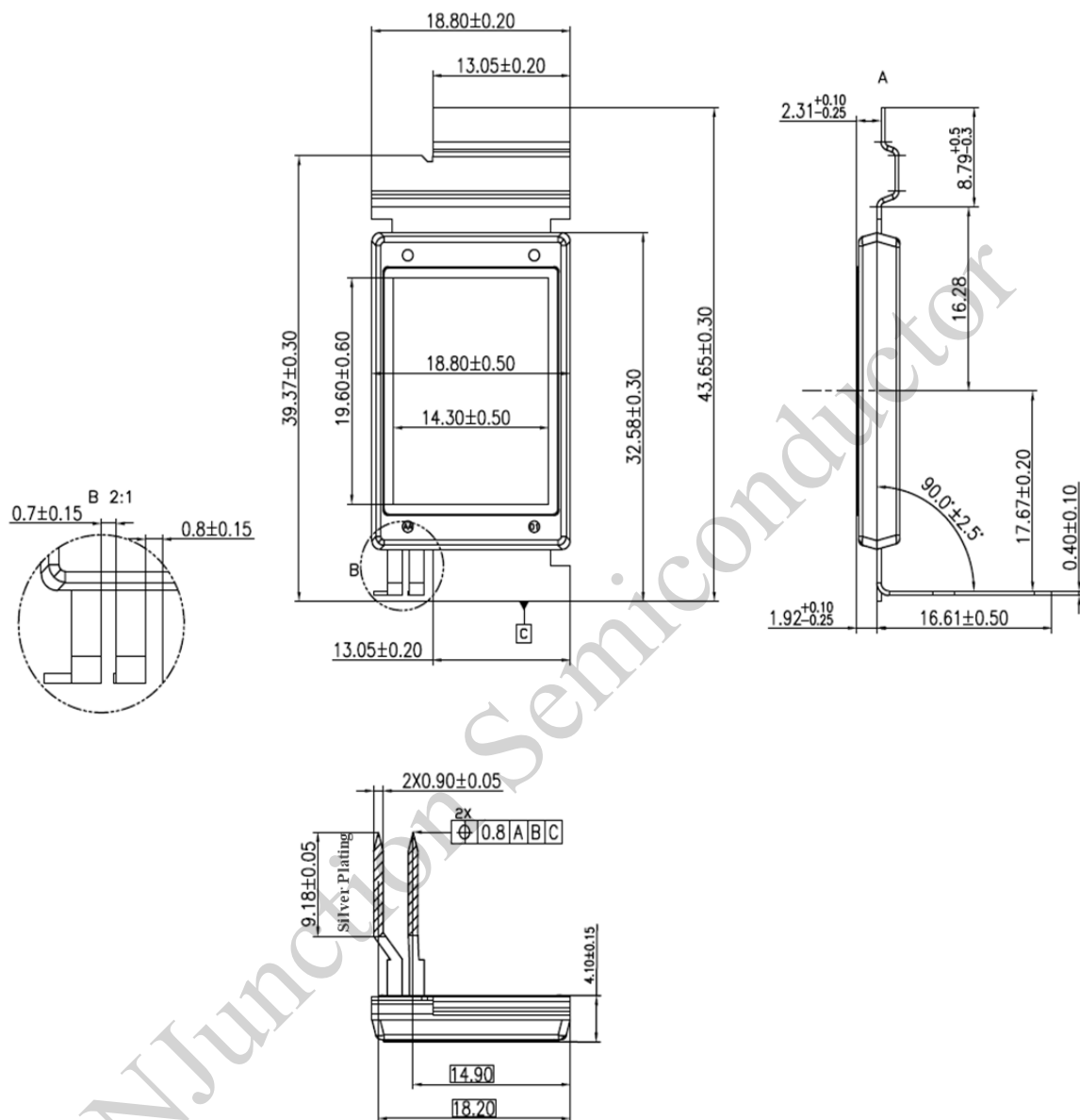


Figure 28. Clamped Inductive Switching Energy vs. Temperature

6. Package Outlines



Drawing and Dimensions

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